

**LP-ISM020**

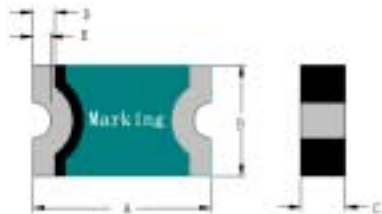
## Features

- Very small size of 0805
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV



## Product Dimensions (mm)

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-ISM020	2.20	1.50	1.00	0.10	0.20



## Electrical Characteristics

Part number	$I_H$ (A)	$I_T$ (A)	$V_{max}$ (V)	$I_{max}$ (A)	$T_{trip}$ Current(A) Time(S)	$Pd_{typ}$ (W)	$R_{min}$ ( $\Omega$ )	$R_{1max}$ ( $\Omega$ )
LP-ISM020	0.20	0.50	9.00	40.0	8.00 0.02	0.5	0.65	3.50

$I_H$ =Hold current: maximum current at which the device will not trip at 25 °C still air.

$I_T$ =Trip current: minimum current at which the device will always trip at 25 °C still air.

$V_{max}$ =Maximum voltage device can withstand without damage at rated current.

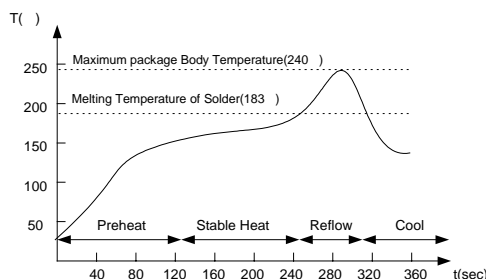
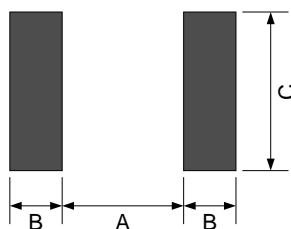
$I_{max}$ =Maximum fault current device can withstand without damage at rated voltage.

$T_{trip}$ =Maximum time to trip(s) at assigned current.

$R_{min}$ =Minimum device resistance at 25 °C prior to tripping.

$R_{1max}$ =Maximum device resistance measured in the nontripped state 1 hour post reflow.

## Solder Reflow Recommendations



## Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-ISM020	1.80	1.00	1.80

\* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

\* Devices can be cleaned using standard industry methods and solvents.

### Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.